

WHAT IS CLAIMED IS;

1. A method for fabricating a circuit device, comprising the steps of:

preparing an insulation resin sheet having the surface of a conductive layer overcoated with insulation resin;

forming through holes in said insulation resin at appointed points on said insulation resin sheet, and selectively exposing the rear side of said conductive layer;

forming a conductive plated layer in said through holes and on the surface of said insulation resin;

forming a first conductive path layer by etching said conductive plated layer to an appointed pattern;

adhering and fixing semiconductor elements on said first conductive path layer with the same electrically insulated therefrom;

overcoating said first conductive path layer and said semiconductor elements with a sealing resin layer;

forming a second conductive path layer by etching said conductive layer to an appointed pattern after making the same thin by etching the entire surface thereof; and

forming external electrodes at appointed points of said second conductive path layers.

2. The method for fabricating a circuit device according to Claim 1, wherein said conductive layer and said conductive plated layer are formed of copper.
3. The method for fabricating a circuit device according to Claim 1, wherein said conductive plated layer is formed to be thin, and said first conductive path layer is finely patterned.
4. The method for fabricating a circuit device according to Claim 1, wherein said conductive layer is formed to be thick, and said conductive layer is used for mechanical support until the step for overcoating with said sealing resin layer is completed.
5. The method for fabricating a circuit device according to Claim 1, wherein said first conductive layer is mechanically supported by said sealing resin layer after the step of overcoating the same with said sealing resin layer.
6. The method for fabricating a circuit device according to Claim 1, wherein said through holes are prepared by laser etching of said insulation resin.
7. The method for fabricating a circuit device according to Claim 6, wherein said laser etching utilizes a carbonic acid gas laser.
8. The method for fabricating a circuit device according

to Claim 1, wherein said conductive plated layer is formed in said through holes and on the surface of said insulation resin by non-electrolytic plating and electrolytic plating of a conductive metal.

9. The method for fabricating a circuit device according to Claim 1, wherein said first conductive path layer is overcoated with overcoating resin with appointed portions thereof not overcoated after said first conductive path layer is formed.

10. The method for fabricating a circuit device according to Claim 9, wherein a layer plated by gold or silver is formed at portions exposed from said overcoating resin of said first conductive path layer.

11. The method for fabricating a circuit device according to Claim 9, wherein said semiconductor elements are adhered to and fixed on said overcoating resin.

12. The method for fabricating a circuit device according to Claim 10, wherein electrodes of said semiconductor elements and said gold- or silver-plated layer are connected to each other by bonding wires.

13. The method for fabricating a circuit device according to Claim 1, wherein said sealing resin layer is formed by a transfer mold.

14. The method for fabricating a circuit device according to Claim 1, wherein said conductive layer is made thin by uniformly etching the entire surface thereof without any mask.

15. The method for fabricating a circuit device according to Claim 1, wherein almost all of the said second conductive path layer is overcoated with overcoating resin.

16. The method for fabricating a circuit device according to Claim 1, wherein said external electrodes have solder adhered thereto by screen printing of solder and are formed by being heated and dissolved.

17. The method for fabricating a circuit device according to Claim 1, wherein said external electrodes are formed by reflowing of solder.

18. The method for fabricating a circuit device according to Claim 1, wherein said external electrodes are formed with the surface thereof plated with gold or palladium by etching said conductive layer to an appointed pattern.